



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



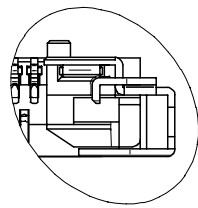
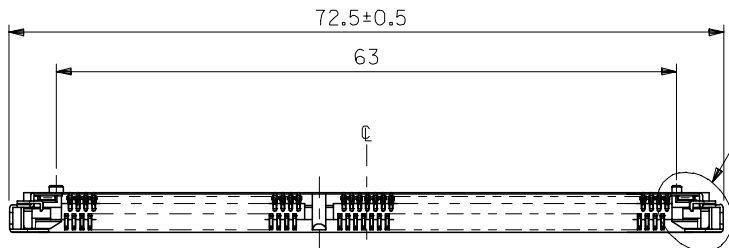
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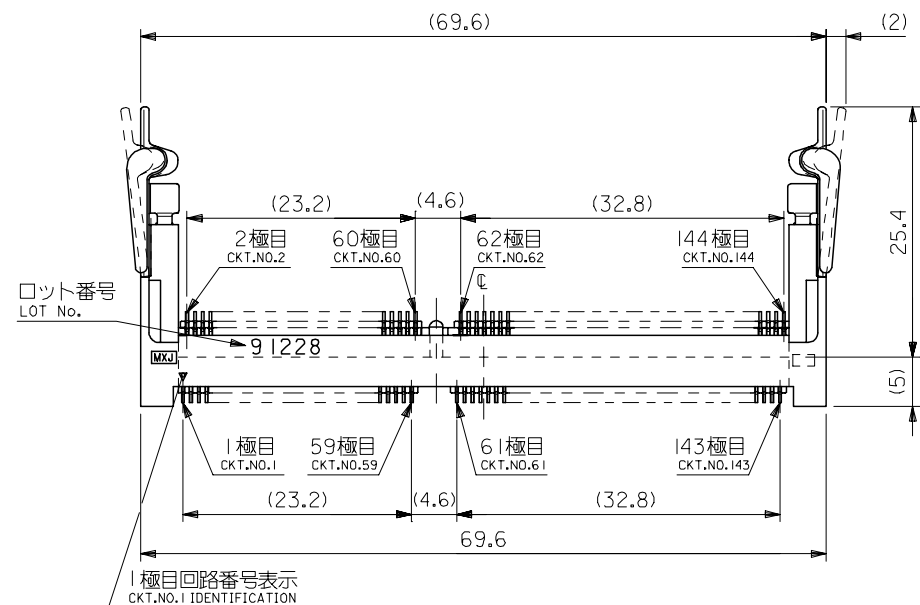
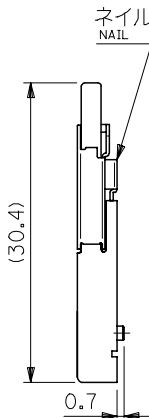


詳細 D
DETAIL D
SCALE 5:1

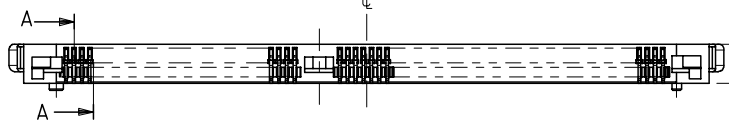
注記 NOTES
1. 材料 MATERIAL
ハウジング : ガラス入り耐熱樹脂、白色、UL94V-0
ターミナル : 燐青銅
TERMINAL : PHOSPHOR BRONZE
ネイル : 黄銅
NAIL : BRASS

2. めっき仕様 PLATING
ロングターミナル LONG TERMINAL
接点部 : 金めっき 0.25μmMIN.
CONTACT AREA : GOLD 0.25 MICROMETER MIN.
半田付け部 : 錫めっき 1.0μmMIN.
SOLDER TAIL AREA : TIN 1.0 MICROMETER MIN.
下地めっき : ニッケルめっき 2.0μmMIN.
UNDER-PLATING : NICKEL 2.0 MICROMETER MIN.
ショートターミナル SHORT TERMINAL
接点部 : 金めっき 0.25μmMIN.
CONTACT AREA : GOLD 0.25 MICROMETER MIN.
半田付け部 : 錫めっき 1.0μmMIN.
SOLDER TAIL AREA : TIN 1.0 MICROMETER MIN.
下地めっき : ニッケルめっき 2.0μmMIN.
UNDER-PLATING : NICKEL 2.0 MICROMETER MIN.
ネイル NAIL
錫めっき : 1.0μmMIN.
TIN : 1.0 MICROMETER MIN.
下地めっき : ニッケルめっき 1.0μmMIN.
UNDER-PLATING : NICKEL 1.0 MICROMETER MIN.

3. テール平坦度は、0.1 MAX. とする。
TAIL COPLANARITY TO BE 0.1 MAX.
ネイル平坦度は、0.1 MAX. とする。
NAIL COPLANARITY TO BE 0.1 MAX.
4. 本製品は 54697-144* の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54697-144*.



1.75	2.85	1.35	3.25	4.05	***V	ハードトレイ (高さ9) HARD TRAY(HIGHT 9)	54697-7008		
						ハードトレイ (高さ11) HARD TRAY(HIGHT 11)	54697-7005		
						標準トレイ NORMAL TRAY	54697-7002		
3.25	1.35	2.85	1.75	5.55	5.0V	ハードトレイ (高さ9) HARD TRAY(HIGHT 9)	54697-7007	54697-700*	144
						ハードトレイ (高さ11) HARD TRAY(HIGHT 11)	54697-7004		
						標準トレイ NORMAL TRAY	54697-7001		
						ハードトレイ (高さ9) HARD TRAY(HIGHT 9)	54697-7006		
2.5	2.1	2.1	2.5	4.8	3.3V	ハードトレイ (高さ11) HARD TRAY(HIGHT 11)	54697-7003		
						標準トレイ NORMAL TRAY	54697-7000		
E	D	C	B	A	POWER SUPPLY	梱包トレイ PACKAGING TRAY	MATERIAL NO.	MODEL NO.	CKT.



MATERIAL 材料
注記参照
SEE NOTES
FINISH 仕上げ
注記参照
SEE NOTES

REVISED EC NO: J2007-0519 DRW:KSAIT001 CHK:D:THARUYAMA APPR:NUKITA	2006/08/25	2006/08/25	2006/09/04	DESCRIPTION A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER		±0.2		DRAWN BY Y.WADA	DATE 2004/05/14	TITLE 0.8MM PITCH S.O.DIMM SOCKET 144CKT H=4 -LEAD FREE-						
	10 OVER 30 UNDER		±0.25		CHECKED BY M.SASAO	DATE 2004/05/14	APPROVED BY M.SASAO 2004/05/14						
	30 OVER		±0.3		APPROVED BY M.SASAO 2004/05/14		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54697-004	SHEET NO. 1 OF 3			
ANGULAR ±3 °					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

F F

E E

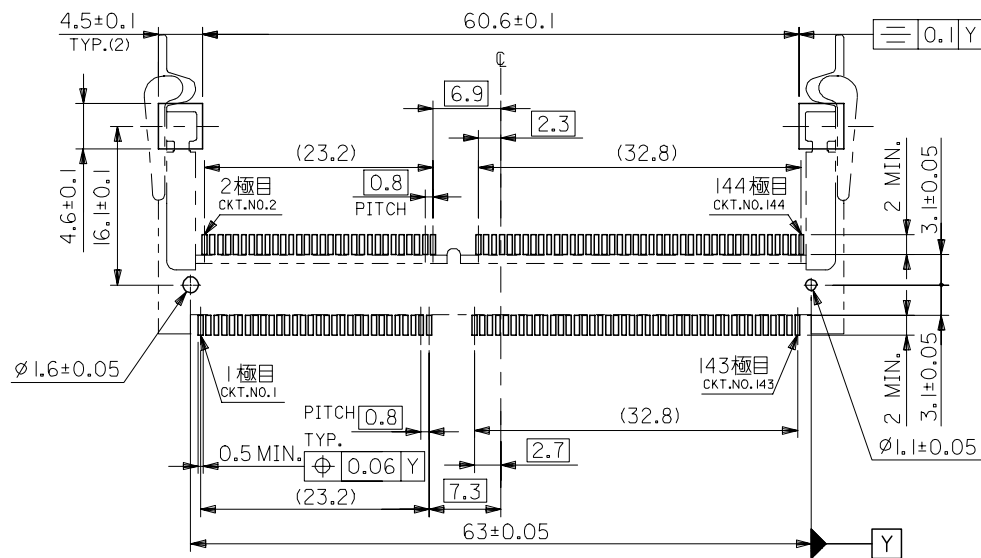
D D

C C

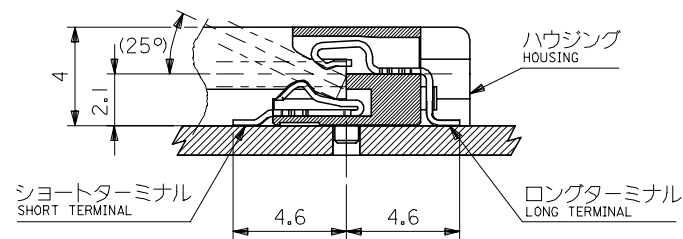
B B

A A

10 9 8 7 6 5 4 3 2 1



推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(THK:1.2±0.1)



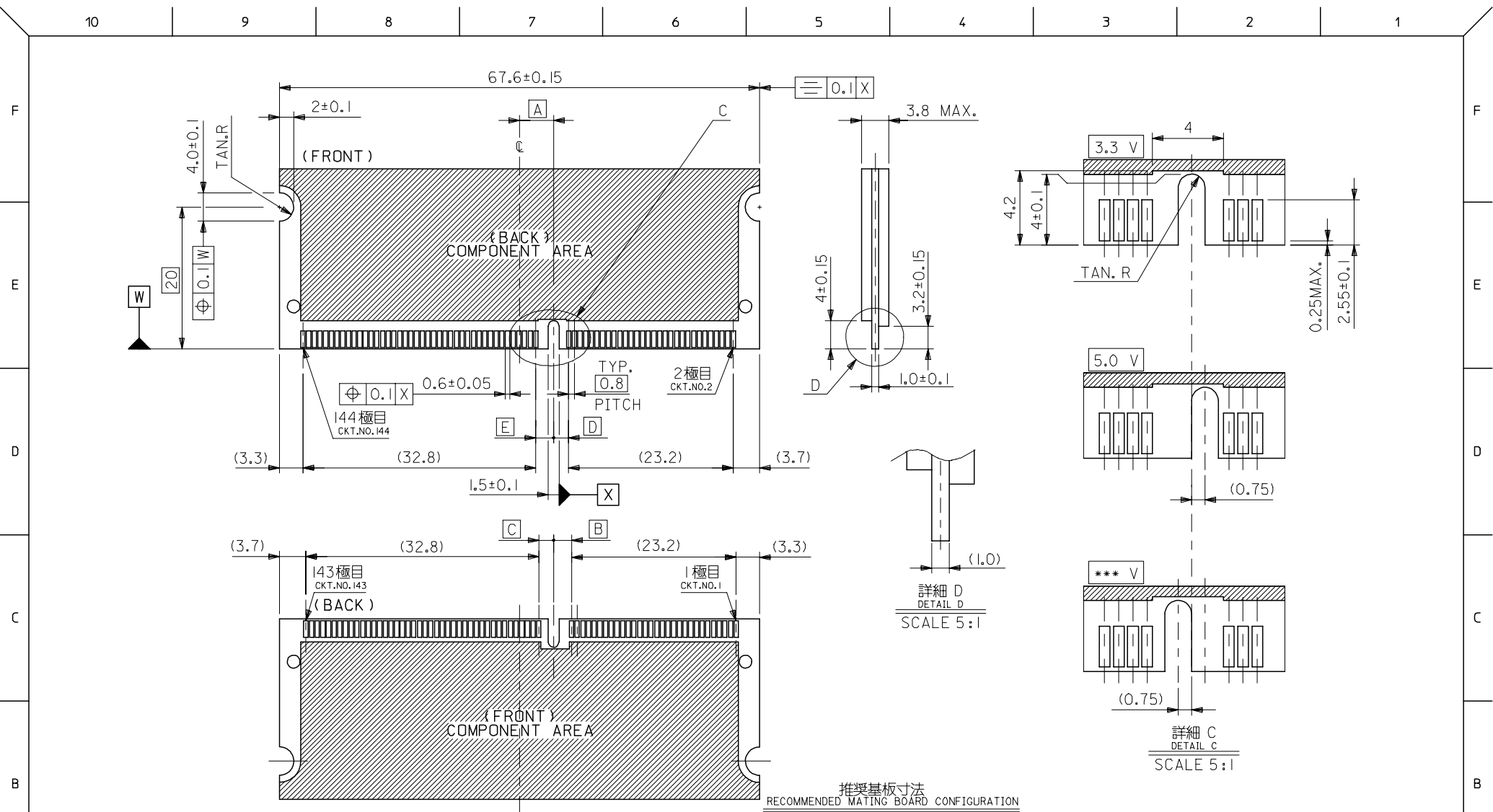
断面 A-A
SECTION A-A
SCALE 5:1

MODEL NO. 54697-700*

MATERIAL 材料
注記参照
SEE NOTES

FINISH 仕上げ
注記参照
SEE NOTES

REVISED EC NO: J2007-0519 DRWNG: SALT001 CHKD: THARUYAMA APPR: NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/05/14	TITLE 0.8MM PITCH S.O.DIMM SOCKET 144CKT H=4 -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/05/14	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/05/14		
A	ANGULAR ±3°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1 OF 3	DOCUMENT NO. SD-54697-004	SHEET NO. 2 OF 3	



推奨基板寸法
RECOMMENDED MATING BOARD CONFIGURATION
(THK: 1.0 ± 0.1)

MATERIAL 材料	注記参照 SEE NOTES
FINISH 仕上げ	注記参照 SEE NOTES

REVISED EC NO: J2007-0519 DRW: KSAIT001 CHKD: THARUYAMA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER ± 0.2	DRAWN BY Y. WADA	DATE 2004/05/14	TITLE 0.8MM PITCH S.O.DIMM SOCKET 144CKT H=4 -LEAD FREE-	
	10 OVER 30 UNDER ± 0.25	CHECKED BY M. SASAO	DATE 2004/05/14	MOLEX INCORPORATED	
	30 OVER ± 0.3	APPROVED BY M. SASAO	DATE 2004/05/14	DOCUMENT NO. SD-54697-004	SHEET NO. 3 OF 3
ANGULAR ± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1 OF 3			
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				